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Vishay Siliconix

Automotive N-Channel 150 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY			
V _{DS} (V)	150		
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.052		
I _D (A)	25		
Configuration	Single		
Package	TO-220		



FEATURES

- TrenchFET® power MOSFET
- Package with low thermal resistance
- 100 % R_q and UIS tested
- AEC-Q101 qualified d
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



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N-Channel MOSFET	
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ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V _{DS}	150		
Gate-Source Voltage		V_{GS}	± 20	V	
Continuous Drain Current	T _C = 25 °C	I _D	25		
	T _C = 125 °C		16		
Continuous Source Current (Diode Conduction) a		I _S	50	Α	
Pulsed Drain Current ^b		I _{DM}	65		
Single Pulse Avalanche Energy	L = 0.1 mH	I _{AS}	30		
Single Pulse Avalanche Current	L = 0.1 IIII	E _{AS}	45	mJ	
Maximum Power Dissipation ^b	T _C = 25 °C	— P₁ I	107	W	
	T _C = 125 °C		35] vv	
Operating Junction and Storage Temperature	e Range	T _J , T _{stg}	-55 to +175	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient	PCB Mount c	R_{thJA}	50	°C/W	
Junction-to-Case (Drain)		R_{thJC}	1.4		

Notes

- a. Package limited.
- b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- c. When mounted on 1" square PCB (FR4 material).
- d. Parametric verification ongoing.



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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static					I.			
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		-	-	V	
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		3	4	V	
Gate-Source Leakage	I _{GSS}	V _{DS} =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 100	nA	
		$V_{GS} = 0 V$	V _{DS} = 150 V	-	-	1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	V _{DS} = 150 V, T _J = 125 °C	-	-	50	μΑ	
		V _{GS} = 0 V	V _{DS} = 150 V, T _J = 175 °C	-	-	250		
On-State Drain Current a	I _{D(on)}	V _{GS} = 10 V	$V_{DS} \ge 5 \text{ V}$	30	-	-	Α	
		V _{GS} = 10 V	I _D = 15 A	-	0.041	0.052		
Drain-Source On-State Resistance a	R _{DS(on)}	V _{GS} = 10 V	I _D = 15 A, T _J = 125 °C	-	-	0.106	Ω	
		V _{GS} = 10 V	I _D = 15 A, T _J = 175 °C	-	-	0.138		
Forward Transconductance b	9 _{fs}	V _{DS}	V _{DS} = 15 V, I _D = 15 A		33	-	S	
Dynamic ^b								
Input Capacitance	C _{iss}			-	1886	2360		
Output Capacitance	C _{oss}	$V_{GS} = 0 V$	V _{GS} = 0 V V _{DS} = 25 V, f = 1 MHz		215	270	pF	
Reverse Transfer Capacitance	C _{rss}			-	97	125	•	
Total Gate Charge ^c	Qg			-	37.9	60		
Gate-Source Charge ^c	Q_{gs}	$V_{GS} = 10 \text{ V}$	$V_{DS} = 75 \text{ V}, I_{D} = 25 \text{ A}$	-	8.5	-	nC	
Gate-Drain Charge ^c	Q_{gd}			-	12.2	-		
Gate Resistance	R_g		f = 1 MHz		1.0	3.2	Ω	
Turn-On Delay Time ^c	t _{d(on)}			-	11	17		
Rise Time ^c	t _r	V_{DD} = 75 V, R_L = 3 Ω I_D \cong 25 A, V_{GEN} = 10 V, R_g = 1 Ω		-	21	33	ns	
Turn-Off Delay Time ^c	t _{d(off)}			-	20	30	115	
Fall Time ^c	t _f			-	12	20		
Source-Drain Diode Ratings and Chara	octeristics ^b							
Pulsed Current ^a	I _{SM}				-	65	Α	
Forward Voltage	V _{SD}	I _F = 20 A, V _{GS} = 0 V		-	0.85	1.5	V	

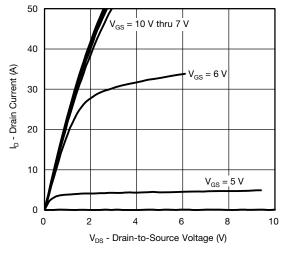
Notes

- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

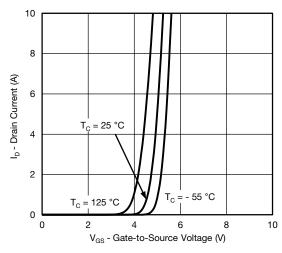
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



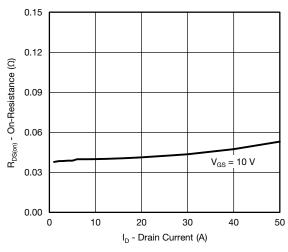
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



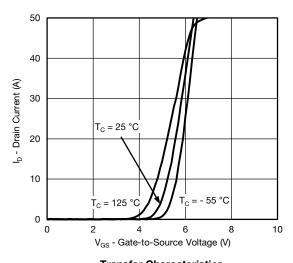
Output Characteristics



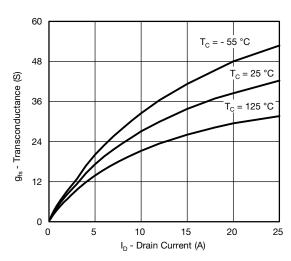
Transfer Characteristics



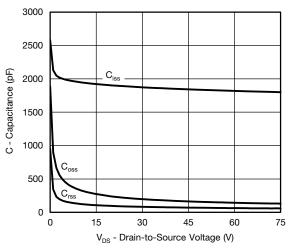
On-Resistance vs. Drain Current



Transfer Characteristics



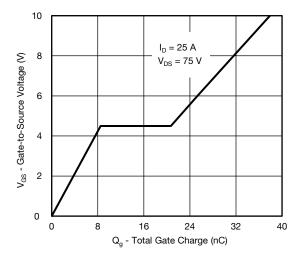
Transconductance



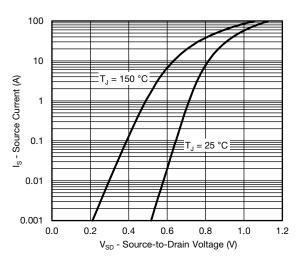
Capacitance



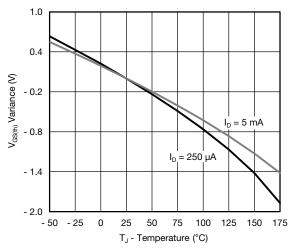
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



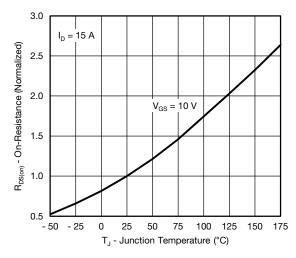
Gate Charge



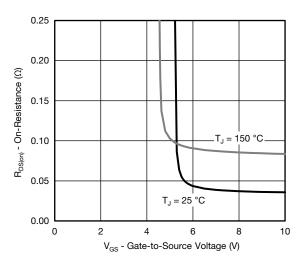
Source Drain Diode Forward Voltage



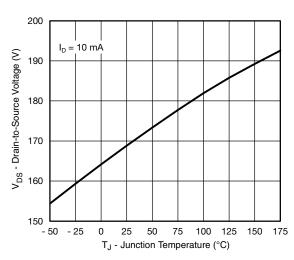
Threshold Voltage



On-Resistance vs. Junction Temperature



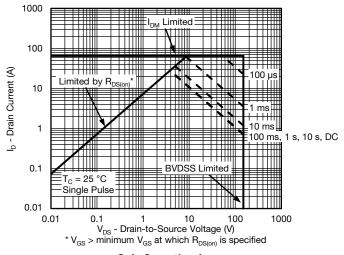
On-Resistance vs. Gate-to-Source Voltage



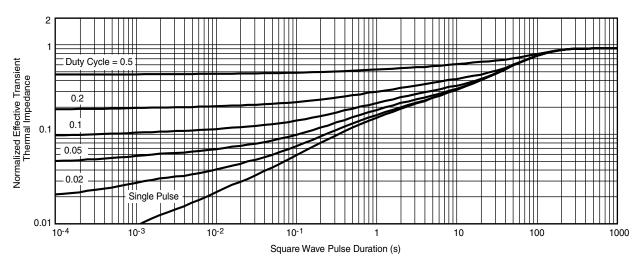
Drain Source Breakdown vs. Junction Temperature



THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)



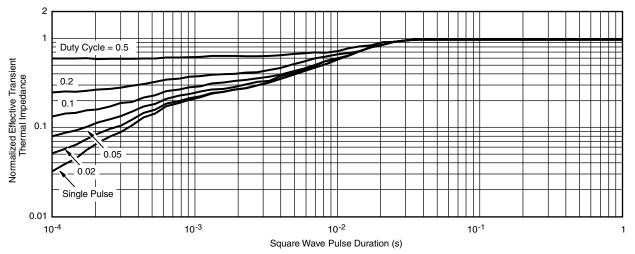
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction to Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction to Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg266974.



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TO-220AB



	D2

	MILLIMETERS		ETERS INCHI	
DIM.	MIN.	MAX.	MIN.	MAX.
А	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
С	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
D2	12.19	12.70	0.480	0.500
Е	10.04	10.51	0.395	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
ØΡ	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118
ECN: T14-0413-Rev. P, 16-Jun-14 DWG: 5471				

Note

 $^{^{\}star}$ M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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